



### POWER DISSIPATION (DFN1616-6)

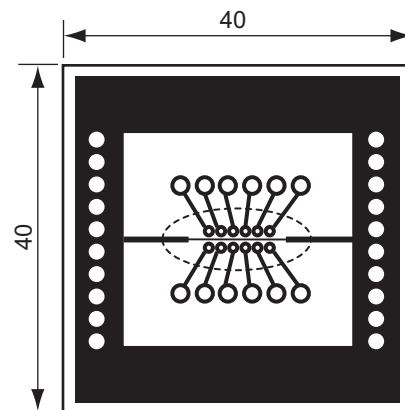
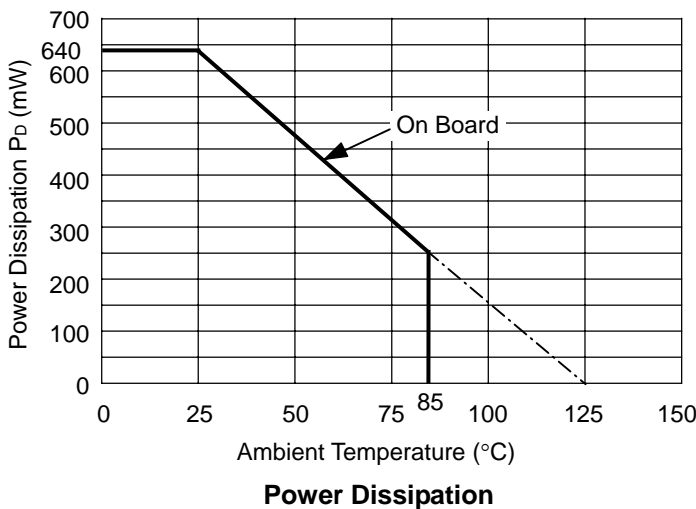
This specification is at mounted on board. Power Dissipation ( $P_D$ ) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

Measurement Conditions

	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	40mm × 40mm × 1.6mm
Copper Ratio	Top side : Approx. 50% , Back side : Approx. 50%
Through-holes	φ0.5mm × 32pcs

Measurement Results (T<sub>opt</sub>=25°C, T<sub>jmax</sub>=125°C)

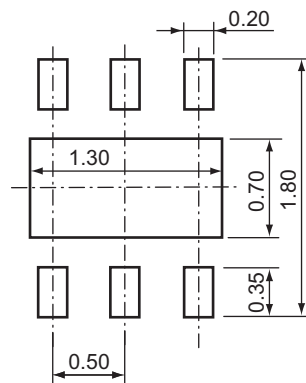
	Standard Land Pattern
Power Dissipation	640mW
Thermal Resistance	$\theta_{ja}=(125-25^{\circ}\text{C})/0.64\text{W}=156^{\circ}\text{C/W}$
Thermal Resistance	$\theta_{jc}=23^{\circ}\text{C/W}$



Measurement Board Pattern

○ IC Mount Area (Unit: mm)

### RECOMMENDED LAND PATTERN



(Unit: mm)